

Type number	Package	Package description	Total product weight
74AXP1G11GS	SOT1202	X2SON6	0.95920 mg

12NC	Version	Pb-free soldering			Pb soldering			Number of processing cycles	Assembly site	RHF-indicator
		MSL	PPT	MPPT	MSL	PPT	MPPT			
935306455125	5	1	260	30 s	1	240	20 s	3	Seremban, Malaysia; Singapore, Singapore; Bangkok, Thailand	

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of subpart	Mass(%) of total product
Die	Doped silicon	Silicon (Si)	7440-21-3	0.02387	100.00000	2.48899
		subTotal		0.02387	100.00000	2.48899
Component	Additive	Non hazardous	Proprietary	0.00025	5.00000	0.02606
	Filler	Bisphenol-A/Epichlorohydrin Epoxy resin (generic)	25068-38-6	0.00025	5.00000	0.02606
		Silica -amorphous-	7631-86-9	0.00250	50.00000	0.26063
		Epoxy resin system	Proprietary	0.00150	30.00000	0.15638
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	0.00050	10.00000	0.05213
subTotal				0.00500	100.00000	0.52126
Lead Frame	Copper alloy	Copper (Cu)	7440-50-8	0.39789	94.51000	41.48114
		Magnesium (Mg)	7439-95-4	0.00063	0.15000	0.06584
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01242	2.95000	1.29478
		Silicon (Si)	7440-21-3	0.00269	0.64000	0.28090
	Pure metal layer	Gold (Au)	7440-57-5	0.00008	0.02000	0.00878
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.00690	1.64000	0.71981
		Palladium (Pd)	7440-05-3	0.00038	0.09000	0.03950
subTotal			0.42100	100.00000	43.89075	
Mould Compound	Additive	Misc. Phosphor compounds (generic)	7723-14-0	0.00049	0.10000	0.05119
		Non hazardous	Proprietary	0.01768	3.60000	1.84279
	Filler	Silica fused	60676-86-0	0.43208	88.00000	45.04587
	Polymer	Carbon black	1333-86-4	0.00098	0.20000	0.10238
		Phenolic resin	Proprietary	0.02013	4.10000	2.09873
	Tetramethylbiphenyl diglycidyl ether	85954-11-6	0.01964	4.00000	2.04754	
subTotal				0.49100	100.00000	51.18850
Wire	Gold alloy	Gold (Au)	7440-57-5	0.01814	99.00000	1.89134
		Palladium (Pd)	7440-05-3	0.00018	1.00000	0.01910
	subTotal				0.01832	100.00000

Note(s):

1) This is a generic description of the substance used as the actual composition of the substances are either considered proprietary or no official CAS number is available. If a CAS number is given, it is the closest match available.

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